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2SK3372

Silicon N-Channel Junction FET

For impedance conversion in low frequency For electret capacitor microphone

■ Features

- High mutual conductance g_m
- Low noise voltage NV

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source voltage (Gate open)	V _{DSO}	20	V	
Gate-drain voltage (Source open)	V_{GDO}	20	V	
Drain-source current (Gate open)	I_{DSO}	2	mA	
Gate-drain current (Source open)	I_{GDO}	2	mA	
Gate-source current (Drain open)	I_{GSO}	2	mA	
Power dissipation	P_{D}	100	mW	
Operating ambient temperature	T _{opr}	-20 to +80	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

■ Package

- Code SSSMini3-F1
- Pin Name
 - 1: Drain
 - 2: Source
 - 3: Gate
- Marking Symbol: 1H

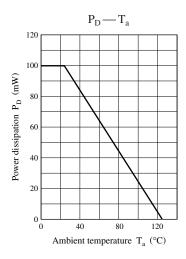
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

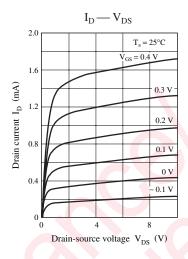
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain current *1	I _D	$V_{DS} = 2.0 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%$	100	-0/1/2	470	μΑ
Drain-source current	I _{DSS}	$V_{DS} = 2.0 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%, V_{GS} = 0$	107	65	460	μΑ
Mutual conductance	g _m	$V_D = 2.0 \text{ V}, V_{GS} = 0, f = 1 \text{ kHz}$	660	1600		μS
Noise voltage	NV	$V_D = 2.0 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%$ $C_O = 5 \text{ pF}, A\text{-Curve}$			4	μV
Voltage gain	G _{V1}	$V_D = 2.0 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%$ $C_O = 5 \text{ pF}, e_G = 10 \text{ mV}, f = 1 \text{ kHz}$	-7.5	-4.7		dB
	G _{V2}	$V_D = 12 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%$ $C_O = 5 \text{ pF}, e_G = 10 \text{ mV}, f = 1 \text{ kHz}$	-4.0	-1.5		
4.	G _{V3}	$V_D = 1.5 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%$ $C_O = 5 \text{ pF}, e_G = 10 \text{ mV}, f = 1 \text{ kHz}$	-8.0	-5.0		
	$\Delta G_{V}.f ^{*2}$	$V_D = 2.0 \text{ V}, R_D = 2.2 \text{ k}\Omega \pm 1\%$ $C_O = 5 \text{ pF}, e_G = 10 \text{ mV}, f = 1 \text{ kHz to } 70 \text{ Hz}$		0	1.7	
Voltage gain difference	$ G_{V2}-G_{V1} $		0		4.0	dB
	$ G_{V1}-G_{V3} $		0		1.7	

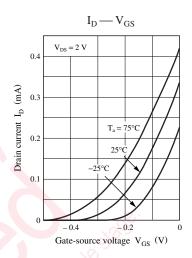
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

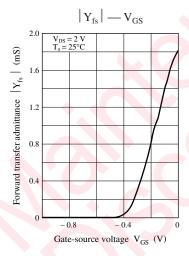
^{2. *1:} I_D is assured for I_{DSS}.

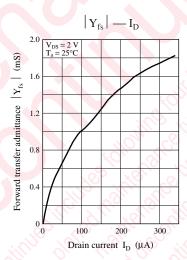
^{*2:} Δ | G_V . f | is assured for AQL 0.065%. (The measurement method is used by source-grounded circuit.)







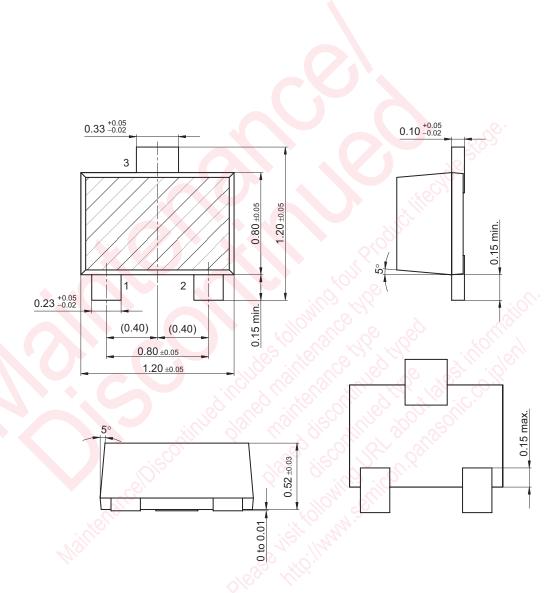




2 SJF00032DED

SSSMini3-F1

Unit: mm



SJF00032DED 3

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